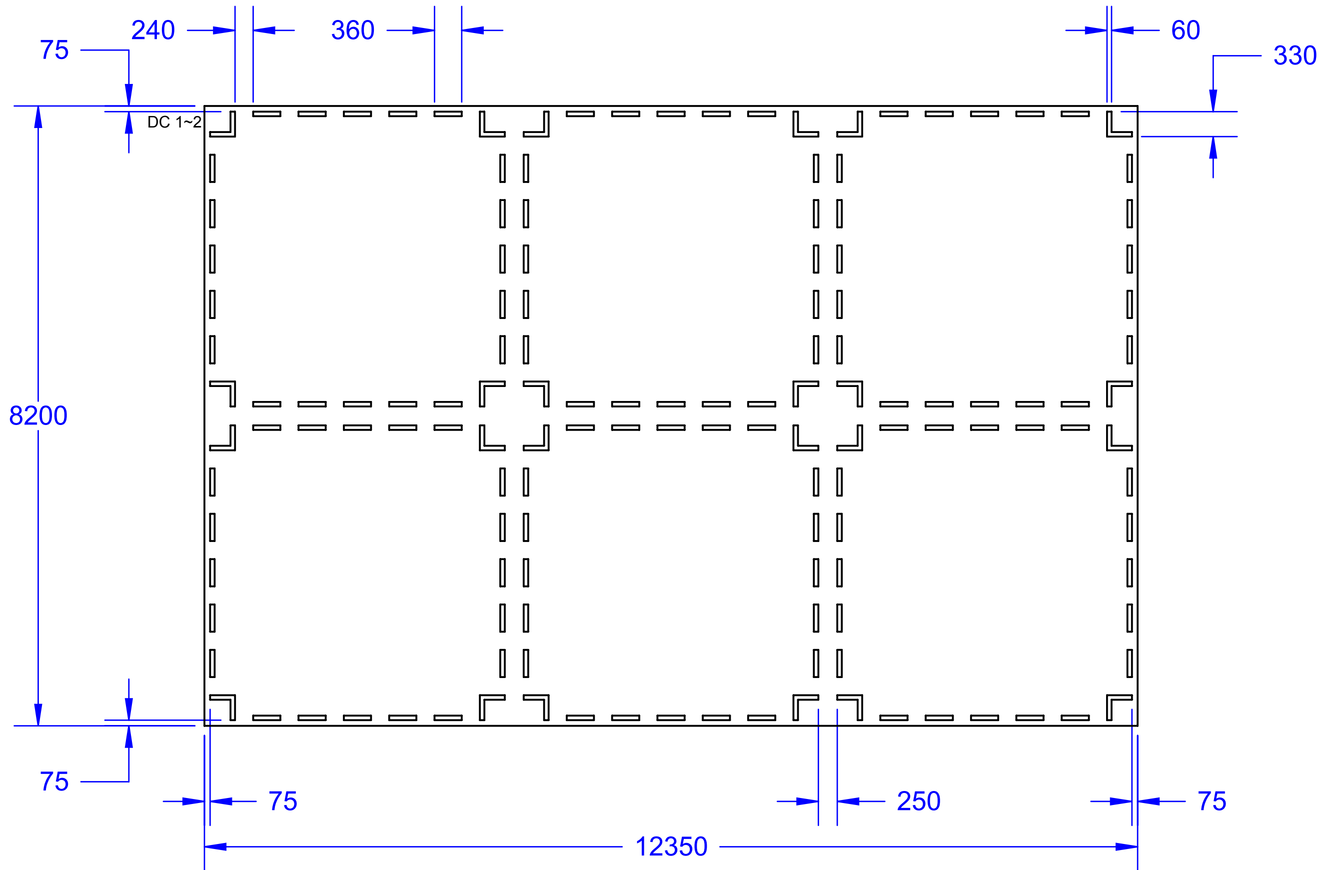
DAISY CHAIN TEST DIE
WIRE BONDABLE
SHOWN WITH CENTER PADS



Notes: (Unless Otherwise Specified)
1. DIE MATERIAL IS SILICON.
2. DIE THICKNESS 250µm ~ 725µm.
3. METALLIZATION 1.0µm ALUMINUM (Al).
4. DIE IS WITHOUT PASSIVATION.
5. WIRE BONDABLE WITH GOLD (Au) WIRE.
6. DAISY CHAIN PAIRS.

APPROVALS		DATE	TopLine®			
DRAWN	T.Au	04/15/14				
ENG	M. Hart	04/15/14	TITLE	DAISY CHAIN TEST DIE TD66 8.2 x 12.5MM		
MFG						
QA			SCALE 10:1	SIZE A	DRAWING NO. 154066	REV A
CUST						
REVISED			DO NOT SCALE DRAWING		SHEET 1 OF 2	

PERIMETER PAD TEST DIE
DAISY CHAIN
SHOWN WITHOUT CENTER PADS FOR CLARITY

240 360 75 60 330

131~132 129~130 127~128 125~126 123~124 121~122 119~120 117~118 115~116 113~114 111~112 109~110 107~108 105~106 103~104 101~102 99~100 97~98 95~96

DC 1~2 3~4 5~6 7~8 9~10 11~12 13~14 15~16 17~18 19~20 21~22 23~24 25~26 27~28

93~94 91~92 89~90 87~88 85~86 83~84 81~82 79~80 77~78 75~76 73~74 71~72 69~70 67~68

8200

29~30 31~32 33~34 35~36 37~38 39~40 41~42 43~44 45~46 47~48 49~50 51~52 53~54 55~56 57~58 59~60 61~62 63~64 65~66

75 75 250 75

12350

SCALE 6:1

DIMENSION IN MICRONS
1.0mm = 1000µm

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